China Semiconductor Technology International Conference (CSTIC) 2022 Summary

June 14-July 12, 2022
MS Teams Live Meeting and SEMI Cloud
Record High 462 submissions from 9 Symposiums

- IX - Design and Automation of Circuits and Systems, 33
- VIII - MEMS, Sensors and Emerging Semiconductor Technologies, 28
- VII - Packaging and Assembly, 25
- VI - Metrology, Reliability and Testing, 46
- V - CMP and Post-Polish Cleaning, 44
- IV - Thin Film, Plating and Process Integration, 75
- III - Dry & Wet Etch and Cleaning, 78
- II - Lithography and Patterning, 57
- I - Device Engineering and Memory Technology, 96

221 Full-Length Manuscripts Published in IEEE Xplore (EI cited)
International Collaboration

845 registrations from 18 countries and regions

Belgium
China Hong Kong
China Mainland
China Taiwan Region
Denmark
France
Germany
Israel
Japan
Korea
Malaysia
Netherlands
Saudi Arabia
Singapore
Sweden
Switzerland
United Kingdom
United States of America
845 registrations + 679 MS Teams Attendees + 55571 Page View
78% registrations from the Industry
23% registrations from Industry Decision Makers
Plenary Speakers

Driving Moore’s Law into the Next Decade
Dr. Martin van den Brink
President and Chief Technology Officer
ASML

Micro-Fabrication Equipment, the Foundation of Digital Revolution and Beyond
Dr. Gerald Yin
Chairman and CEO
AMEC

Advanced 3D Chiplet Packaging Technology and Manufacturing
Dr. Marvin Liao
Vice President, APTS
TSMC

An Innovative 3D HITOC 4F² DRAM Architecture
Dr. Feng Hong
CEO
ICLeague Technology
9 Symposia with 100 Invited Speakers

Symp I: Device Engineering and Memory Technology
Symp. II: Lithography and Patterning
Symp. III: Dry & Wet Etch and Cleaning
Symp. IV: Thin Film, Plating and Process Integration
Symp. V: CMP and Post-Polish Cleaning
Symp. VI: Metrology, Reliability and Testing
Symp. VII: Packaging and Assembly
Symp. VIII: MEMS, Sensors and Emerging Semiconductor Technologies
Symp. IX: Design and Automation of Circuits and Systems

Virtual Conference: June 14-July 12  v.semi.org.cn/cstic
WFD Training Course

Development of Integrated Process for CMOS
Jiang Yan
North China University of Technology
June 14, 2022

2017 - present
Dean /Professor
Electronics Engineering Department, North China University of Technology

2009 – 2017
Professor at Institute of Microelectronics of Chinese Academy of Sciences
Research for 14nm FDSOI and 22nm bulk technology

July’99 – July’09
Infineon Technologies (East Fishkill, NY, USA)
Process Engineer / Project manager
>180 Participating Companies

3M
Advantest
Air Products
AMEC
Anji
APC Worldwide
Applplied Materials
ASE
ASM
ASML
Avantor Sciences
Axcelis
Baker Hughes
Beijing Institute of Technology
Beijing Normal University
Beijing Superstring Academy of Memory Technology
Beijing University of Posts and Telecommunications
Beijing University Of Technology
Berkeley
BESI
Brew Science
Cabot
Cambridge University
Central South University
CGP Tech Fund
Chartwell
China University of Mining and Technolog
Chinese Academy of Science, China
Clarkson University
Corning

CSMC
CXMT
Cymer
Dalian University of Technology
Dartbond
Design2Silicon
Digital China
Dow
Duke
Dupont
East China Normal University
Edwards Vacuum
Enflame Tech
Entegris
ESWIN
Eurofins EAG Materials
Fortune Precision Equipment
Fraunhofer
Fudan University
Fujifilm
Fuzhou University
Gefran Automation Technology
Giga Photon
Grandit
Grimm
Guangdong University of Technology
Guangxi University
Han Top Photo Materials
Hanyang University
Hebei University of Technology

Henkel
HFC Semiconductor
HHGrace
Hikstor Technology
Hitachi High Tech
HLMC
Horiba
Huahai New Materials
Huawei
Huazhong University of Science and Technology
IBM
ICleague
ICMITIA
ICRD
IMEC
Info VC
Informatik Uni-Bremen
Institute of Computing Technology, Chinese Academy of Science
Institute of Semiconductor, Chinese Academy of Sciences
Institute of Semiconductor, Guangdong Academy of Sciences
Intel
JCET
JCET Semiconductor Integration (Shaoxing)
Jiangsu Industrial Technology Research Institute
Jiangsu Normal University
Jiangyin high tech Zone Investment Promotion Bureau
JSR
King Abdullah University of Science & Technology
King Semi
Kioxia
>180 Participating Companies

KLA
Kolusai Electric
Lam Research
Lanzhou University of Technology
Lead Micro
Leuven Instruments
Linx Consulting
Mattson
Mentor
Merck
Midsx
Minghsin University of Science and Technology
Mingqi Consulting
Mito Kogyo
MKS
Mycronic
Nanjing University
Nata Opto-electronic Material
National Central University
National Chiao Tung University
National Taiwan University of Science and Technology
Naura
Ningbo University
Nissan Chem
North China University of Technology
Nouryon
NXF
Onto Innovation
Osaka Vacuum
Peking University

Photronics
Piotech
Politecnico Di Milano
Proximus
Rainbow Material
Repro
Ruiixin International
Samsung
Sane Chips
Scientific Visual
Semitop
Seoul National University
SGS Semiconductor
Shanghai ICRD
Shanghai Industrial Technology Research Institutes
Shanghai Jiaotong University
Shanghai Micro Electronics Equipment
Shanghai Tech University
Shanghai University
Shanghai University of Technology
Shinhao Materials
SHPP (Shanghai)
Sinyang
Sky Semiconductor
SMIC Beijing
SMIC Shanghai
SMNC
Southeast University
Southern University of Science and Technology
Stanford

STR Software
Synopsys
Sypio Tech
System Plus
Technical University of Munich, Germany
TEL
Tenfeng Technology
Teradyne
Tsinghua University
TSMC
Tuqijing Technology
TZTEK
UnilC Semiconductor
University of Electronic Science and Technology
University of Michigan-Shanghai Jiao Tong University Joint Institute
University of Notre Dame, USA
University of Pittsburgh
Uppsala University
VAT
Wintech Nano-Technology
Xiamen University
Xilinx
Xinfa Electronic Technology
XMC Wuhan
Yonsei University
Yuan-Ze University, Taiwan
Zeiss
Zhejiang University
ZJU-Hangzhou Global Scientific and Technological Innovation Center
ZTE
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Conference Chair

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IBM, USA

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Chair, S-VII
JCET, China

Dr. Qinghuang Lin
Chair, S-VIII
Lam, USA

Dr. Zhuo Cheng
Chair S-IX
Zhejiang Univ.
China

Dr. Hsiang-Lan Lung
Chair Poster
Macronix, Taiwan, China
COVID-19 Plague in Shanghai

• More than 600,000 positive patients or asymptomatic patients had been confirmed, while 588 death had been certified by government during April and May in Shanghai.
• Committees and SEMI China president had to make the decision to transfer to virtual conference in late April.
• By combining MS Teams live meeting and SEMI cloud website, CSTIC 2022 has successfully overcome all the difficulties brought by COVID-19. Speakers and attendees have communicated quite well and great result have been achieved.

Source: Baidu
Special Thanks to Sponsors and Co-organizers

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Organizers: SEMI, IEEE

Co-organizers: IMECAS, IAMST

Co-sponsors: Electron Device Society, MIRS

Proceedings Publication: IEEE
CSTIC 2023

Time: March 20 ~ 21, 2023

Venue: Shanghai International Convention Center (SHICC)

Call for Papers Deadline: Nov. 1, 2022
Thank you!